## **REMARKS**

#### INTRODUCTION

In accordance with the foregoing, claims 32, 34 and 36 have been amended and claims 20-31 have been withdrawn. Claims 1-19 and 32-36 are pending in the application.

### **OBJECTION TO THE DRAWINGS**

The drawings are objected to because it is not clear from Fig. 10F if the chamber/nozzle plate layer 108 should be in the scribe lane area or the main chip area. It is submitted that the lead line coming from reference numeral 108, denoting the chamber/nozzle plate layer first described in paragraph [0056] of the specification, leads to a layer in the scribe lane area that has been appropriately marked. A chamber/nozzle plate having ink chambers formed in the main chip area is described in paragraph [0081] but is not shown in the drawings.

Withdrawal of the foregoing objection is requested.

## **CLAIM REJECTIONS – 35 U.S.C. § 102**

Claims 32-36 were rejected under 35 U.S.C. 102(b) as being anticipated by Hess et al. (U.S. 5,122,812) (hereinafter "Hess").

Hess discloses a thermal inkjet print head having driving circuitry thereon and a method for making the same. In Hess, a portion 120 of protective material is positioned on top of the underlying conductive material layers. The portion 120 of protective material actually includes four main layers. A first passivation layer 122 is provided which consists of silicon nitride. Layer 122 is applied by the PECVD of silicon nitride resulting from the decomposition of silane mixed with ammonia at a pressure of about 2 torr and temperature of about 300-400 degrees C. The layer 122 covers the resistor 109 and the transistor 74 as illustrated. The main function of the passivation layer 122 is to protect the resistor 109 and other components from the corrosive action of the ink used in the cartridge. This is especially important with respect to resistor 109, since any physical damage thereto can dramatically impair its basic operational capabilities. Hess, 7:28-7:45

Further, The portion 120 of protective material also includes a second passivation layer 123 which is preferably manufactured of silicon carbide. Hess, 7:48-7:50.

### Claim 32 and 33

Amended claim 32 recites: "...a scribe lane area disposed around the main chip area and forming a cutting region in which the main chip area is divided from main chip areas of other print heads; and a damping portion on the outerscribe lane area of the main chip area..." In contrast to amended claim 32, Hess does not disclose a scribe lane area forming a cutting region dividing the main chip areas of other print heads.

Claim 33 depends on claim 32 and is therefore believed to allowable for the foregoing reasons.

Withdrawal of the foregoing rejection is requested.

#### Claims 34 and 35

Amended claim 34 recites: "...a scribe lane area disposed around the main chip area and forming a cutting region in which the main chip area is divided from main chip areas of other print heads by cutting; and a damping portion on the outerscribe lane area of the main chip area..." In contrast to amended claim 34, Hess does not disclose a scribe lane area forming a cutting region dividing the main chip areas of other print heads by cutting.

Claim 35 depends on claim 34 and is therefore believed to allowable for the foregoing reasons.

Withdrawal of the foregoing rejection is requested.

### Claim 36

Amended claim 36 recites: "...a scribe lane area disposed around the main chip area and forming a cutting region; and a damping portion on the outerscribe lane area of the main chip area..." In contrast to amended claim 36, Hess does not disclose a scribe lane area forming a cutting region.

Withdrawal of the foregoing rejection is requested.

## **ALLOWABLE CLAIMS**

The Applicant acknowledges with appreciation that claims 1-19 have been allowed.

# CONCLUSION

There being no further outstanding objections or rejections, it is submitted that the application is in condition for allowance. An early action to that effect is courteously solicited.

Finally, if there are any formal matters remaining after this response, the Examiner is requested to telephone the undersigned to attend to these matters.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

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